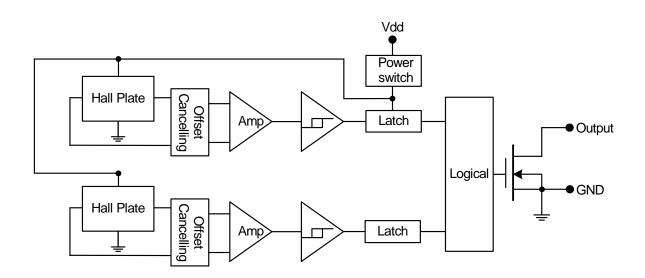


Pin Descriptions

Pin Name	P/I/O	Description
Vdd	P/I	Power Supply Input
GND	P/I	Ground
Output	0	Output Pin
NC	NC	No Connected

Functional Block Diagram



Absolute Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Symbol	Parameter	Rating	Unit
V _{dd}	Supply Voltage	7	V
В	Magnetic Flux Density	Unlimited	
T _{STG}	Storage Temperature Range	-65 to +150	°C
PD	Package Power Dissipation	230	mW
TJ	Maximum Junction Temperature	+150	°C

Recommended Operating Conditions

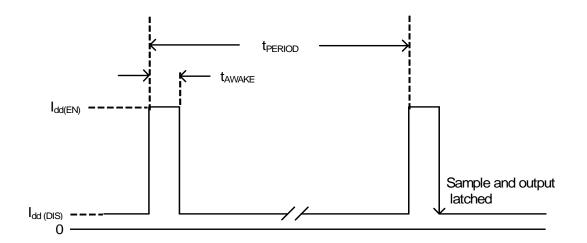
Symbol	Parameter	Conditions	Rating	Unit
V _{dd}	Supply Voltage	Operating	2.5 to 5.5	V
T _A	Operating Temperature Range	Operating	-40 to +85	°C



Electrical Characteristics (@T_A = +25°C, V_{dd} = 3V, unless otherwise specified.)

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
V _{OUT}	Output On Voltage	I _{OUT} =1mA		0.1	0.3	V
IOFF	Output Leakage Current	V _{OUT} =5.5V, Output off		<0.1	1	μA
I _{dd(EN)}		Chip enable, $T_A = +25^{\circ}C$, $V_{dd} = 3V$		3	6	mA
I _{dd(EN)}		Chip enable, T_A =-40 to +85°C, V _{dd} = 2.5V to 5.5V	_	3	10	mA
I _{dd(DIS)}		Chip disable, T_A = +25°C, V_{dd} = 3V		5	10	μA
I _{dd(DIS)}	Supply Current	Chip disable, T_A = -40 to +85°C, V _{dd} = 2.5V to 5.5V	_	5	18	μA
I _{dd(AVG)}		Average supply current, T_A = +25°C, V _{dd} = 3V	_	8	16	μA
I _{dd(AVG)}		Average supply current, T _A = -40 to +85°C, V _{dd} = 2.5V to 5.5V	_	8	28	μA
f _C	Chopping Frequency	For design information only		300		kHz
t AWAKE	Awake Time	(Note 6)		75	150	μs
t PERIOD	Period	(Note 6)		75	150	ms
D.C.	Duty Cycle		_	0.1	_	%

Notes: 6. When power is initially on, the operating V_{dd} (2.5V to 5.5V) must be applied to be guaranteed for the output sampling. The output state is valid after the second operating phase (typical 150ms).



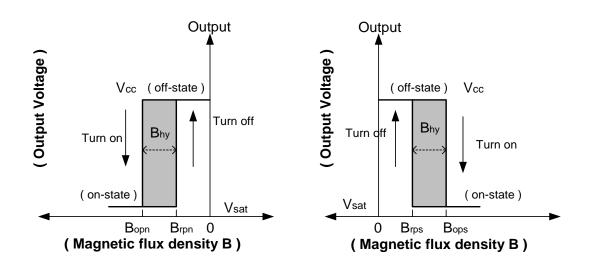


Magnetic Characteristics (@T_A = +25°C, V_{dd} = 3V, unless otherwise specified. Notes 7 and 8)

					(1mT=10 Gauss
Symbol	Characteristic	Min	Тур	Max	Unit
Bops(South Pole to Brand Side)	Operate Daint		28	55	
Bopn(North Pole to Brand Side)	Operate Point	-55	-28	_	
Brps(South Pole to Brand Side)	Deleges Deint	10	20	_	Gauss
Brpn(North Pole to Brand Side)	Release Point		-20	-10	
Bhy(Bopx-Brpx)	Hysteresis	5	8	_	

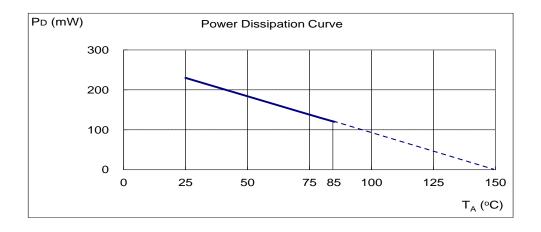
Notes:

7. Typical data is at T_A= +25°C, V_{dd} = 3V, and for design information only. 8. Operating point and release point will vary with supply voltage and operating temperature.



Performance Characteristics

	T _A (°C)	25	50	60	70	80	85	90	100	110	120	130	140	150
ſ	P _D (mW)	230	184	166	147	129	120	110	92	74	55	37	18	0





AH 1822 - XXX - 7 Package Packing

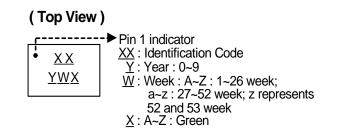
FT4: X2-DFN2015-6

7 : Tape & Reel

Device	Package Code	Packaging	7" Tape	and Reel				
Device	Fackage Coue	Fackaging	Quantity	Part Number Suffix				
AH1822-FT4-7	FT4	X2-DFN2015-6	3000/Tape & Reel -7					
Note: 9. For packaging det	ote: 9. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.							

Marking Information

(1) X2-DFN2015-6



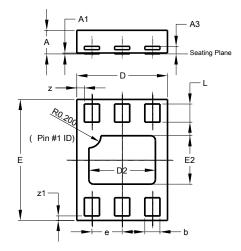
Part Number	Package	Identification Code
AH1822	X2-DFN2015-6	К7



Package Outline Dimensions (All dimensions in mm.)

Please see http://www.diodes.com/package-outlines.html for the latest version.

(1) Package Type: X2-DFN2015-6

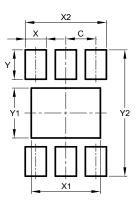


)	X2-DFN2015-6					
Dim	Min	Max	Тур			
Α	0.375	0.40	0.390			
A1	0	0.05	0.02			
A3	-	-	0.13			
b	0.20	0.30	0.25			
D	1.45	1.575	1.50			
D2	1.00	1.20	1.10			
е	-	-	0.50			
E	1.95	2.075	2.00			
E2	0.70	0.90	0.80			
L	0.25	0.35	0.30			
Z	-	-	0.125			
Z1	-	-	0.075			
All D	imens	ions ir	n mm			

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

(1) Package type: X2-DFN2015-6

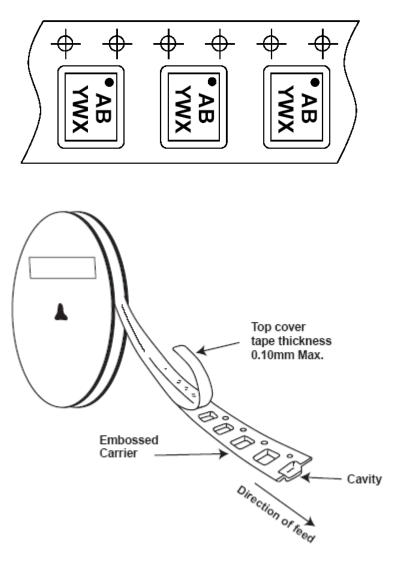


X2-DFN2015-6				
Dimensions	Value (in mm)			
C	0.500			
Х	0.350			
X1	1.150			
X2	1.350			
Y	0.500			
Y1	0.850			
Y2	2.150			



Taping Orientation

(1) X2-DFN2015-6



Notes: 10. The taping orientation of the other package type can be found on our website at http://www.diodes.com/datasheets/ap02007.pdf.



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